

ABSTRACT OF THE DISCLOSURE

It is possible to obtain a clean high-quality circuit board by removing affected material and foreign matter produced when a hole is formed. A manufacturing method of the circuit board includes (a) preparing a film-coated board material by bonding a film material as a mask to a board material, (b) forming a hole in the film-coated board material by applying a laser beam thereto, and (c) selectively removing the unnecessary material sticking to the film-coated board material from the film-coated board material by supersonic cleaning without peeling the film material off the board material. Unnecessary material such as foreign matter is produced when the hole is formed, and the unnecessary material sticks to the board material. After removal of such unnecessary material, a conductive material is disposed in the hole, using the film material as a mask, and the film material is later removed from the board material.